

IN THE CLAIMS:

Please AMEND claims 37, 38, 42, 43, 47, 48, 52, 53, 57 and 58, as follows. For the Examiner's convenience, all claims currently pending in this application have been reproduced below:

1-36. (Canceled)

37. (Currently Amended) An electrostatic sensing apparatus having an electrode for sensing a surface position of a shot region in a substrate to which a pattern is transferred by an exposure apparatus, said ~~electronic~~ electrostatic sensing apparatus comprising:

a plurality of ~~detection sections~~ the electrodes; and

a system which selects at least one ~~detection section~~ electrode from said plurality of ~~detection sections~~ electrodes, based on layout information of the shot region to be detected, and calculates the surface position based upon an output of said selected at least one ~~detection section~~ electrode.

38. (Currently Amended) An exposure apparatus for transferring a pattern to a shot region in a substrate, said apparatus comprising:

an electrostatic sensor, for sensing a surface position of the shot region, having a plurality of ~~detection sections~~ electrodes; and

a system which selects at least one ~~detection-section~~ electrode from said plurality of ~~detection-sections~~ electrodes, based on layout information of the shot region to be detected, and calculates the surface position based upon an output of said selected at least one ~~detection-section~~ electrode.

39-41.(Canceled)

42. (Currently Amended) A ~~device manufacturing~~ method of manufacturing a device, said method comprising steps of:

transferring a pattern to a substrate using an exposure apparatus as defined in claim 38; and

developing the substrate to which the pattern has been transferred; and
processing the developed substrate to manufacture the device.

43. (Currently Amended) An exposure apparatus for transferring a pattern to a shot region in a substrate, said apparatus comprising:

a plurality of electrostatic sensors, for sensing a surface position of the shot region, each having a plurality of ~~detection-sections~~ electrodes; and

a system which selects at least one ~~detection-section~~ electrode from said plurality of ~~detection-sections~~ electrodes of said plurality of electrostatic sensors, based on layout information of the shot region to be detected, and calculates the surface position based upon

outputs an output of said selected at least one ~~detection section of said one of said plurality of electrostatic sensors~~ electrode.

44-46. (Canceled)

47. (Currently Amended) A ~~device manufacturing method~~ of manufacturing a device, said method comprising steps of:

transferring a pattern to a substrate using an exposure apparatus as defined in claim 43; ~~and~~

developing the substrate to which the pattern has been transferred; and
processing the developed substrate to manufacture the device.

48. (Currently Amended) A scanning exposure apparatus for transferring a pattern of a mask to a shot region in a substrate by scanning the mask and the substrate relative to a slit-shaped exposure beam, said apparatus comprising:

an electrostatic sensor, for sensing a surface position of the shot region, having a plurality of ~~detection sections~~ electrodes arranged in a direction perpendicular to a scanning direction of the mask and the substrate; and

a system which selects at least one ~~detection section~~ electrode from said plurality of ~~detection sections~~ electrodes, based on layout information of the shot region to be detected,

and calculates the surface position based upon an output of said selected at least one ~~detection section~~ electrode.

49-51. (Canceled)

52. (Currently Amended) A ~~device manufacturing method~~ of manufacturing a device, said method comprising steps of:

transferring a pattern to a substrate using a scanning exposure apparatus as defined in claim 48; ~~and~~

developing the substrate to which the pattern has been ~~transferred~~ transferred; and
processing the substrate to manufacture the device.

53. (Currently Amended) A scanning exposure apparatus for transferring a pattern of a mask to a shot region in a substrate by scanning the mask and the substrate relative to a slit-shaped exposure beam, said apparatus comprising:

a plurality of electrostatic sensors, for sensing a surface position of the shot region, each having a plurality of ~~detection sections~~ electrodes arranged in a direction perpendicular to a scanning direction of the mask and the substrate; and

a system which selects at least one ~~detection section~~ electrode from said plurality of ~~detection sections~~ electrodes of one of said plurality of electrostatic sensors based on layout information of the shot region to be detected, and calculates the surface position based upon

~~outputs an output~~ of said selected at least one ~~detection section of said one of said plurality of electrostatic sensors~~ electrode.

54-56. (Canceled)

57. (Currently Amended) A ~~device manufacturing method~~ of manufacturing a device, said method comprising steps of:

transferring a pattern to a substrate using a scanning exposure apparatus as defined in claim 53; ~~and~~

developing the substrate to which the pattern has been transferred; and
processing the developed substrate to manufacture the device.

58. (Currently Amended) An apparatus according to claim 48, wherein said plurality of ~~electrostatic sensors~~ electrodes are arranged at a plurality of positions in the scanning direction.

59. (Previously Presented) An apparatus according to claim 53, wherein said plurality of electrostatic sensors are arranged at a plurality of positions in the scanning direction.

60. (Previously Presented) An apparatus according to claim 37, wherein the layout information includes information of at least one of a dimension in the shot region, a position of the shot region in the substrate, and an arrangement of chip regions in the shot region.

61. (Previously Presented) An apparatus according to claim 38, wherein the layout information includes information of at least one of a dimension of the shot region, a position of the shot region in the substrate, and an arrangement of chip regions in the shot region.

62. (Previously Presented) An apparatus according to claim 48, wherein the layout information includes information of at least one of a dimension of the shot region, a position of the shot region in the substrate, and an arrangement of chip regions in the shot region.

63. (Previously Presented) An apparatus according to claim 53, wherein the layout information includes information of at least one of a dimension of the shot region, a position of the shot region in the substrate, and an arrangement of chip regions in the shot region.